









Description

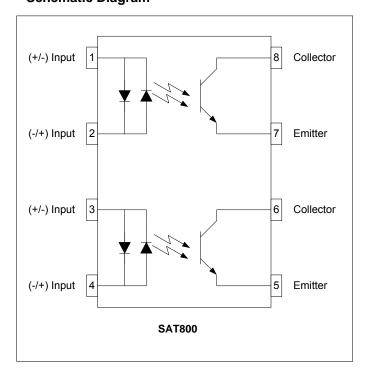
The SAT800 consists of two phototransistors, each optically coupled to two light emitting diodes for AC input operation. Optical coupling between the input IR LED and output phototransistor allows for high isolation levels while maintaining low-level DC signal control capability. The SAT800 provides an optically isolated method of controlling many interface applications such as telecommunications, industrial control and instrumentation circuitry.

The SAT800 comes standard in a miniature 8 pin DIP package.

Applications

- Registers, Copiers, Automatic Vending Machines
- System Appliances, Measuring Instruments
- Computer Terminals, PLCs
- Telecommunication Equipment, Telephones
- Home Appliances
- **Digital Logic Inputs**
- Microprocessor Inputs
- Switching Power Supplies

Schematic Diagram



Features

- $V_{CEO} = 60V$
- Small 8 pin DIP/SMD package
- Low input power consumption
- High stability
- CTR Range 20 300%
- High Isolation Voltage (5000V_{RMS})
- Long Life / High Reliability
- RoHS / Pb-Free / REACH Compliant

Agency Approvals

UL/C-UL: File # E201932

VDF: File # 40035191 (EN 60747-5-2)

Absolute Maximum Ratings

The values indicated are absolute stress ratings. Functional operation of the device is not implied at these or any conditions in excess of those defined in electrical characteristics section of this document. Exposure to absolute Maximum Ratings may cause permanent damage to the device and may adversely affect reliability.

Storage Temperature	55 to +125°C
Operating Temperature	40 to +100°C
Continuous Input Current	50mA
Transient Input Current	500mA
Reverse Input Control Voltage	6V
Input Power Dissipation ¹	40mW
Total Power Dissipation ¹	300mW
Solder Temperature – Wave (10sec)	260°C
Solder Temperature – IR Reflow (10sec)	260°C

NOTES

1. **Power Dissipation per Channel**

Ordering Information

Part Number	Description
SAT800	8 pin DIP, (50/Tube)
SAT800-H	0.40" (10.16mm) Lead Spacing (VDE0884)
SAT800-S	8 pin SMD, (50/Tube)

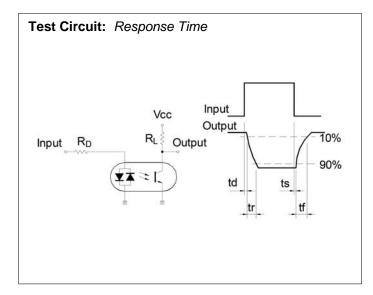
SAT800-STR 8 pin SMD, Tape and Reel (1000/Reel)

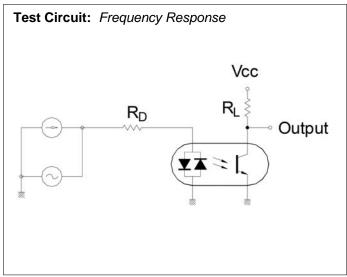
NOTE: Suffixes listed above are not included in marking on device for part number identification



Electrical Characteristics, T_A = 25°C (unless otherwise specified)

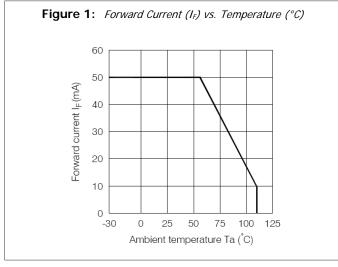
Parameter	Symbol	Min.	Тур.	Max.	Units	Test Conditions
Input Specifications						
LED Forward Voltage	V _F	-	1.2	1.4	V	I _F = ±20mA
Terminal Capacitance	Ct	-	50	250	pF	V=0, f=1KHz
Output Specifications						
Collector-Emitter Voltage	V _{CEO}	60	-	-	V	I _C =10μA
Emitter-Collector Voltage	V _{COE}	6	-	-	V	I _E =10μA
Collector Dark Current	I _{CEO}	-	-	100	nA	V _{CE} =20V
Floating Capacitance	C _f	-	0.6	1.0	pF	V _{CE} =0, f=1MHz
Cut-Off Frequency	f _C	-	80	-	kHz	V_{CE} =5V, I_{C} =2mA, R_{L} =100 Ω , -3dB
Saturation Voltage	V _{CE(sat)}	-	0.1	0.2	V	I _F =±20mA, I _C =1mA
Coupled Specifications						
Rise Time	T _R	-	4.0	18.0	μS	$I_C=\pm 2mA$, $V_{CC}=2V$, $R_L=100\Omega$
Fall Time	T _F	-	3.0	18.0	μS	$I_C=\pm 2mA$, $V_{CC}=2V$, $R_L=100\Omega$
Current Transfer Ratio	CTR	20	-	300	%	I _F =±1mA, V _{CE} =5V
CTR Classification (BINNING)						
- A		50	-	150	%	I _F =±1mA, V _{CE} =5V
- E		20	-	300	%	I _F =±1mA, V _{CE} =5V
Isolation Specifications						
Isolation Voltage	V _{ISO}	5000	-	-	V _{RMS}	RH ≤ 50%, t=1min
Input-Output Resistance	R _{I-O}	-	10 ¹²	-	Ω	V _{I-O} = 500V _{DC}

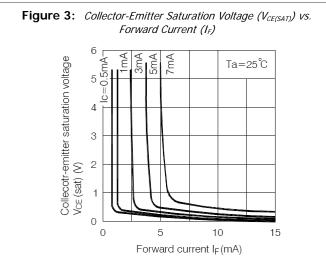


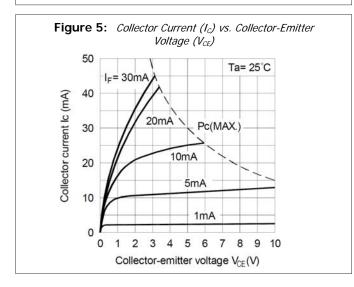


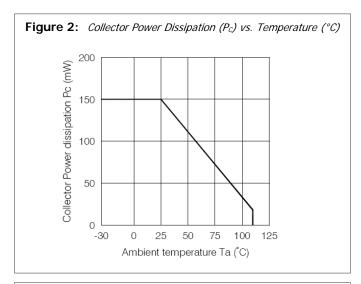


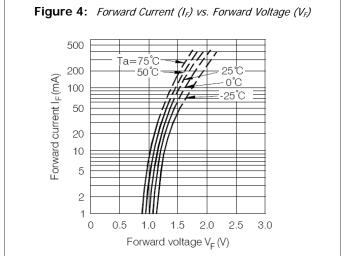
SAT800 Performance & Characteristics Plots, T_A = 25°C (unless otherwise specified)

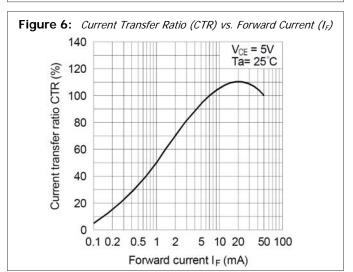








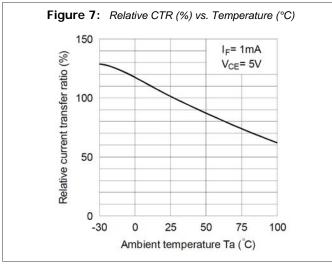


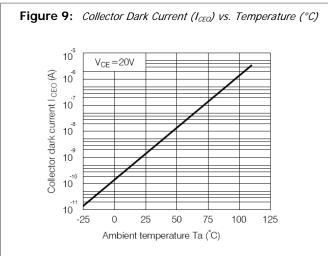


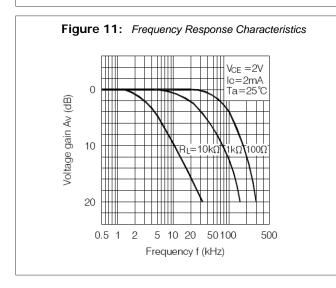
60V

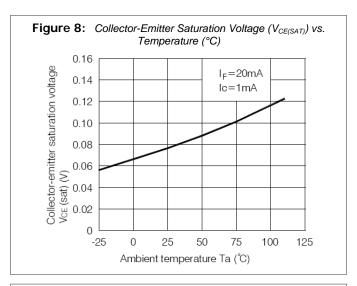


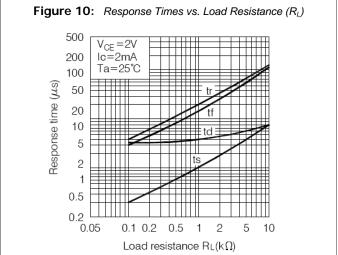
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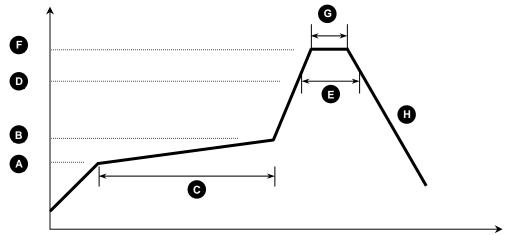




SAT800 Solder Reflow Temperature Profile Recommendations

(1) Infrared Reflow:

Refer to the following figure as an example of an optimal temperature profile for single occurrence infrared reflow. Soldering process should not exceed temperature or time limits expressed herein. Surface temperature of device package should not exceed 250°C:



Process Step	Description	Parameter
Α	Preheat Start Temperature (°C)	150°C
В	Preheat Finish Temperature (°C)	180°C
С	Preheat Time (s)	90 - 120s
D	Melting Temperature (°C)	230°C
E	Time above Melting Temperature (s)	30s
F	Peak Temperature, at Terminal (°C)	260°C
G	Dwell Time at Peak Temperature (s)	10s
Н	Cool-down (°C/s)	<6°C/s

(2) Wave Solder:

Maximum Temperature: 260°C (at terminal)

Maximum Time: 10s

Pre-heating: 100 - 150°C (30 - 90s)

Single Occurrence

(3) Hand Solder:

Maximum Temperature: 350°C (at tip of soldering iron)

Maximum Time:

Single Occurrence

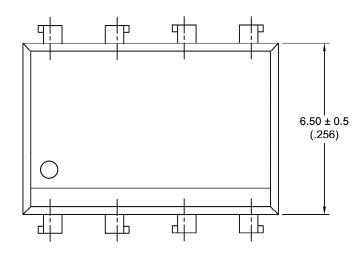
3s (at tip of)

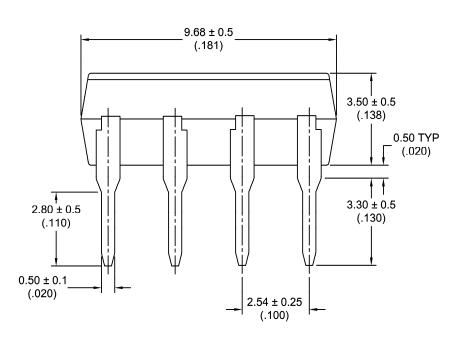


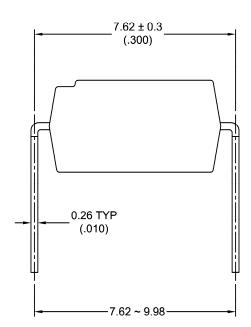


SAT800 Package Dimensions

8 PIN DIP Package





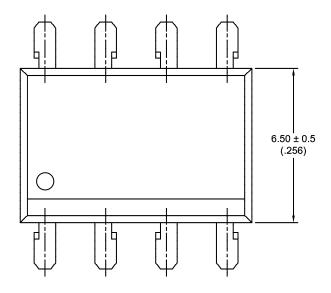


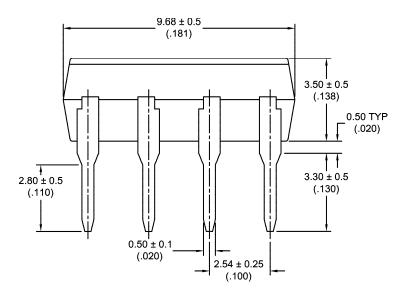


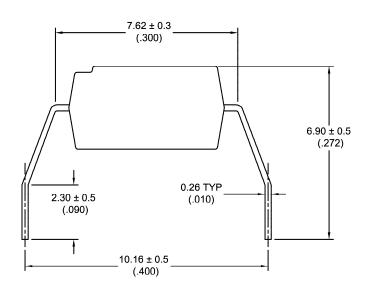


SAT800 Package Dimensions

8 PIN WIDE Lead Space Package (-H)



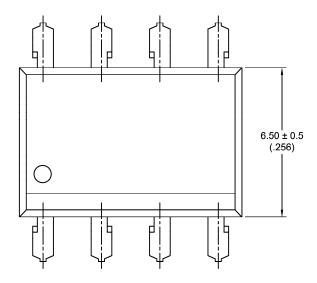


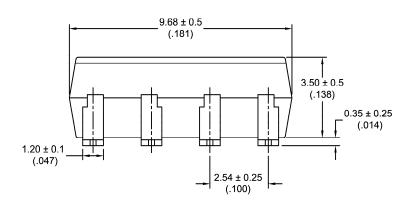


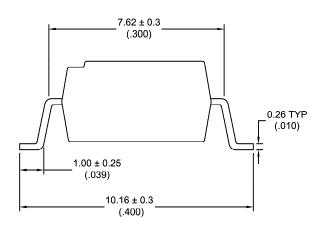


SAT800 Package Dimensions

8 PIN SMD Surface Mount Package (-S)



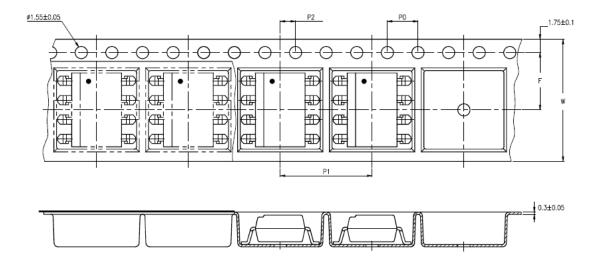






SAT800 Packaging Specifications

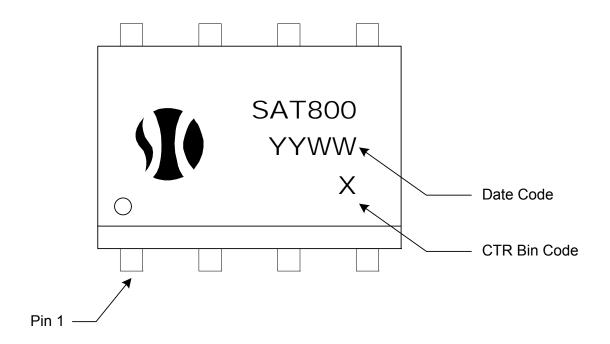
Tape & Reel Specifications (T&R)



Specification	Symbol	Dimensions, mm (inches)
Tape Width	W	16 \pm 0.3 (0.63)
Sprocket Hole Pitch	P0	4 ± 0.1 (0.15)
Compartment Location	F P2	7.5 ± 0.1 (0.295) 2 ± 0.1 (0.079)
Compartment Pitch	P1	12 ± 0.1 (0.472)



SAT800 Packaging Marking



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